

FINAL CALL FOR PAPERS

SEPTEMBER 13–16, 2022

ESTC 2022

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The Electronics System-Integration Technology Conference (ESTC) is the premier international event in the field of electronics packaging and system integration. The conference is organized every two years in Europe and is supported by IEEE-EPS in association with IMAPS-Europe. The 9th ESTC will be taking place in Sibiu, Romania. Placed in the middle of Romania, surrounded by the high Carpathian Mountains and Cibin river, Sibiu is a citadel of the European electronics industry and represents a place where culture, landscape, gastronomy and profession merge in a friendly pleasant environment.

The ESTC 2022 seeks original, noncommercial papers describing research and innovations in all areas of electronics packaging and system integration. Authors are invited to submit an abstract describing recent work. Abstracts must detail the objectives of the work presented and demonstrate new results.

Proposed Topics:

- Advanced packaging
- Materials for interconnects and packaging
- Optoelectronic systems packaging
- Assembly and manufacturing technologies
- Design tools and modeling
- Power electronics system packaging
- Advanced technologies for emerging systems
- Reliability and quality of electronic devices and systems
- Flexible, printed and hybrid electronics
- RF, mm-wave and THz systems packaging
- Global education for electronics

The technical program will include oral talks, poster presentations, an exhibition, special sessions and invited keynote talks given by renowned speakers.

Proceedings

Accepted contributions will be published in the conference proceedings, and archived in IEEE Xplore (provided they comply with specifications). ESTC papers can be searched through IEEE, Google scholar and other search engines.

Sponsors and exhibitors welcome!

The ESTC 2022 offers attractive packages for sponsors and exhibitors! Please contact local committee for further details.

Important dates:

Conference: 13 – 16 September 2022
Abstract submission opens: 1 December 2021
Abstract submission deadline: 01 March 2022
Abstract acceptance notification: 31 March 2022
Paper submission deadline: 15 June 2022

Please check the Conference website for details on hotel bookings and travel arrangements.

Venue

Ramada Hotel
Sibiu, Romania

Contact

Local Conference Committee
Email: estc@estc-conference.net
Website: <https://www.estc-conference.net>

Organizers



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